

CLAIMS

1. A wiring of a semiconductor device comprising:
 - a first conductive layer formed on a semiconductor substrate;
 - a first insulation layer formed on said first conductive layer, planarized by a CMP
5 process and having a scratch on a surface thereof;
 - a second insulation layer formed on said first insulation layer;
 - a second conductive layer contacting said first conductive layer through a via hole
formed in said first and second insulation layers; and
 - a third conductive layer formed in a groove formed in said second insulation layer,
10 wherein said groove has a depth less than a thickness of said insulation layer.
2. A wiring of a semiconductor device as claimed in claim 1, wherein said first
and second insulation layers are formed from a same insulation material.
3. A wiring of a semiconductor device as claimed in claim 1, wherein said
second conductive layer comprises a plug filling said via hole.
- 15 4. A wiring of a semiconductor device as claimed in claim 1, wherein said first
conductive layer is an impurity doped region on said semiconductor substrate.
5. A wiring of a semiconductor device as claimed in claim 1, further
comprising:

a third insulation layer formed on said second insulation layer, having a second via hole therein; and

a fourth conductive layer formed on said third insulation layer, contacting said third conductive layer through said second via hole.

5 6. A wiring of a semiconductor device as claimed in claim 5, wherein said fourth conductive layer is a bit line formed from a conductive material selected from a group consisting of tungsten, aluminum and copper.

10 7. A wiring of a semiconductor device comprising:
a first conductive layer formed on a semiconductor substrate;
a first insulation layer formed on said first conductive layer, planarized by a CMP process and having a scratch on a surface thereof;

a second insulation layer formed on said first insulation layer and having a groove formed therein; and

15 a second conductive layer formed in said groove, having a thickness thinner than a thickness of said second insulation layer.

8. A wiring of a semiconductor device as claimed in claim 7, wherein said first and second insulation layers are formed from a same insulation material.

9. A wiring of a semiconductor device as claimed in claim 7, wherein said

second conductive layer is formed from a metal selected from a group consisting of tungsten, aluminum and copper.

10. A method of manufacturing a wiring of a semiconductor device comprising the steps of:

- 5 forming a first conductive layer on a semiconductor substrate;
- forming a first insulation layer on said conductive layer by depositing a first insulating material and implementing a CMP process;
- 10 forming a second insulation layer by depositing a second insulation material on said first insulation layer in order to cover a scratch formed on said first insulation layer after implementing said CMP process;
- forming an etching pattern by etching said second insulation layer to a thickness less than a thickness of said second insulation layer; and
- 15 forming a conductive pattern of a second conductive layer having a damascene shape by depositing a conductive material on said etching pattern and then planarizing the second conductive layer.

11. A method of manufacturing a wiring of a semiconductor device as claimed in claim 10, wherein said first and second insulation materials are the same.

12. A method of manufacturing a wiring of a semiconductor device as claimed in claim 11, wherein said first insulation material and said second insulation material are

silicon oxide.

13. A method of manufacturing a wiring of a semiconductor device as claimed in claim 10, wherein said first insulation material is silicon oxide.

14. A method of manufacturing a wiring of a semiconductor device as claimed in claim 10, wherein said second insulation material is silicon oxide.

15. A method of manufacturing a wiring of a semiconductor device as claimed in claim 10, further comprising a step of forming a second etching pattern by etching said first and second insulation layers.

16. A method of manufacturing a wiring of a semiconductor device as claimed in claim 10, wherein said conductive material is selected from a group consisting of tungsten, aluminum and copper.

17. A method of manufacturing a wiring of a semiconductor device as claimed in claim 10, wherein said planarizing of said conductive layer is implemented by a CMP process.